$I_{FAV} = 2x 20 A$



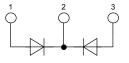
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Sonic Fast Recovery Diode

High Performance Fast Recove Low Loss and Soft Recovery Common Cathode

Part number

DHG 40 C 1200 HB



1

1200 V

75 ns

Backside: cathode

Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
- Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package:

 $V_{RRM} =$

- Housing: TO-247
- Industry standard outline
- Epoxy meets UL 94V-0
- · RoHS compliant

Ratings

Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RRM}	max. repetitive reverse voltage		$T_{VJ} = 25^{\circ}C$			1200	V
I _R	reverse current	V _R = 1200 V	$T_{VJ} = 25^{\circ}C$			30	μΑ
		V _R = 1200 V	$T_{VJ} = 125$ °C			3	mΑ
V _F	forward voltage	I _F = 20 A	$T_{VJ} = 25^{\circ}C$			2.69	V
		$I_F = 40 A$				3.52	V
		I _F = 20 A	T _{VJ} = 150°C			2.35	V
		$I_F = 40 A$				3.29	V
I _{FAV}	average forward current	rectangular, d = 0.5	$T_c = 85^{\circ}C$			20	Α
V_{F0}	threshold voltage		$T_{VJ} = 150$ °C			1.60	V
r _F	slope resistance	calculation only				33.8	mΩ
R _{thJC}	thermal resistance junction to case					0.90	K/W
T _{VJ}	virtual junction temperature			-55		150	°C
P_{tot}	total power dissipation		$T_c = 25^{\circ}C$			140	W
I _{FSM}	max. forward surge current	t = 10 ms (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			135	Α
I _{RM}	max. reverse recovery current		$T_{VJ} = 25^{\circ}C$		19		Α
		$I_F = 20 \text{ A}; V_R = 800 \text{ V}$	$T_{VJ} = ^{\circ}C$		tbd		Α
t _{rr}	reverse recovery time	$-di_F/dt = 750 A/\mu s$	$T_{VJ} = 25^{\circ}C$		75		ns
			$T_{VJ} = ^{\circ}C$		tbd		ns
CJ	junction capacitance	$V_R = 600 V; f = 1 MHz$	$T_{VJ} = 25^{\circ}C$		tbd		pF

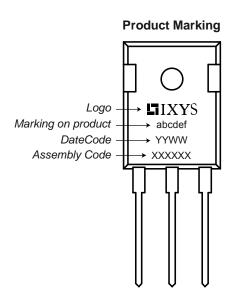


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Ratings

Symbol	Definition	Conditions	mi	ո. typ	. max.	Unit
I _{RMS}	RMS current	per pin ¹⁾			50	Α
R _{thCH}	thermal resistance case to heatsink			0.2	5	K/W
T _{stg}	storage temperature		-	55	150	°C
Weight					6	g
M _D	mounting torque		(8.0	1.2	Nm
F _c	mounting force with clip			20	120	N

¹⁾ I_{RMS} is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip. In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.



Part number

D = Diode

H = Sonic Fast Recovery Diode

G = extreme fast

40 = Current Rating [A]

C = Common Cathode 1200 = Reverse Voltage [V] HB = TO-247AD (3)

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	DHG 40 C 1200 HB	DHG40C1200HB	Tube	30	505138

Similar Part	Package	Voltage class		
DHG40C1200PB	TO-220	1200		
DHG40C600HB	TO-247	600		
DHG40C600PB	TO-220	600		

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